

CLAIMS

1) A method for bonding a porous material to a substantially non-porous material comprising:

- a) supplying a substantially non-porous substrate having a bonding surface and a plurality of substrate apertures, having an aperture width and an aperture depth,
- b) dispensing an amount of adhesive onto the bonding surface to at least partially fill with adhesive at least a portion of the substrate apertures,
- c) pressing a porous material and the substantially non-porous material together at the bonding surface, and
- d) curing the adhesive while the porous material remains in contact with the bonding surface.

2) The method for bonding a porous material to a substantially non-porous material of claim 1 wherein the porous material and the substantially non-porous material are pressed together with enough force such that only a residue of adhesive remains on the bonding surface.

3) The method for bonding a porous material to a substantially non-porous material of claim 1 wherein the adhesive becomes is a low viscosity adhesive for at least a portion of the curing step.